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(71) Applicant (for all designated States except US):
S.O.I.TEC SILICON ON INSULATOR TECHNOLOGIES [FR/FR]; Parc Technologique des Fontaines,
Chemin des Franques, F-38190 Bernin (FR).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **ARENA, Chantal**
[US/US]; 3847 E. Ivyglen Circle, Mesa, Arizona 85205
(US). **WERKHOVEN, Christiaan** [NL/US]; 107 North
Nielson Lane, Gilbert, Arizona 85234 (US).

(74) Agents: **FANUCCI, Allan, A.** et al.; Winston & Strawn
LLP, Patent Department, 1700 K Street, N.W., Washington,
District of Columbia 20006-3817 (US).

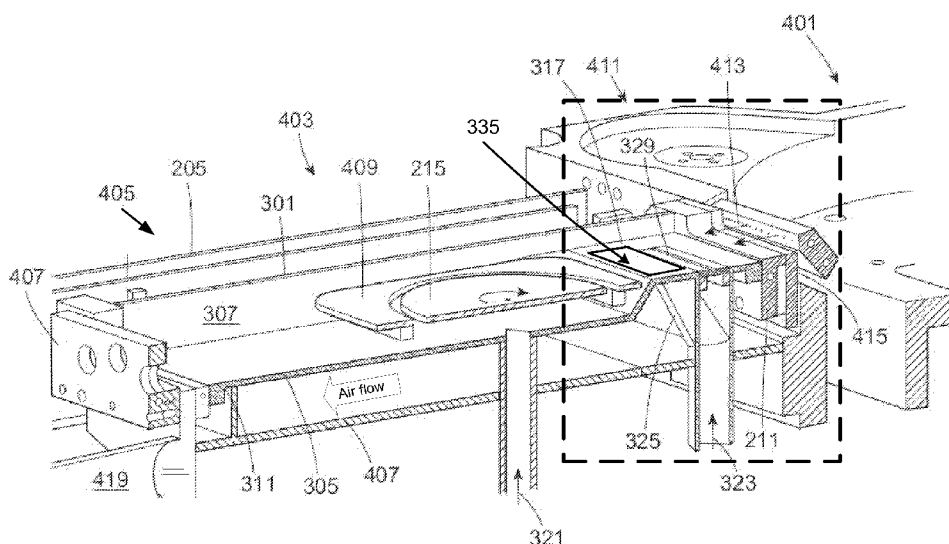
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(54) Title: GALLIUM TRICHLORIDE INJECTION SCHEME



(57) Abstract: The present invention is related to the field of semiconductor processing equipment and methods and provides, in particular, methods and equipment for the sustained, high-volume production of Group III-V compound semiconductor material suitable for fabrication of optic and electronic components, for use as substrates for epitaxial deposition, for wafers and so forth. In preferred embodiments, these methods are optimized for producing Group III-N (nitrogen) compound semiconductor wafers and specifically for producing GaN wafers. Specifically, the method includes reacting an amount of a gaseous Group III precursor as one reactant with an amount of a gaseous Group V component as another reactant in a reaction chamber under conditions sufficient to provide sustained high volume manufacture of the semiconductor material on one or more substrates, with the gaseous Group III precursor continuously provided at a mass flow of 50 g Group III element/hour for at least 48 hours. A system for conducting the method is also provided.

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